

What is claimed is:

1. An electronic component, comprising:

a piezo-electric resonator which is formed on an element substrate and which has a piezo-electric film, said piezo-electric resonator obtaining a signal having a predetermined resonant frequency by a bulk wave propagating
5 within said piezo-electric film;

a mounting substrate on which said piezo-electric resonator is mounted by a face-down bonding through N electrically connected projecting portions;
and

when a maximum diameter of said N electrically connected projecting
10 portions is defined as D μm after said piezo-electric resonator is mounted on said mounting substrate, the shear strength of said N electrically connected projecting portions being not smaller than $ND/6$ (g).

2. An electronic component as claimed in claim 1, wherein said die shear strength of said N electrically connected projecting portions being not smaller than $ND/3.6$ (g).

3. An electronic component as claimed in claim 1, wherein said N electrically connected projecting portions are formed by gold.

4. An electronic component as claimed in claim 1, wherein said piezo-electric resonator is an SMR type piezo-electric resonator.

5. An electronic component as claimed in claim 1, wherein said piezo-electric resonator has an acoustic multi-layer film between said element substrate and said piezo-electric film.

6. An electronic component as claimed in claim 1, wherein a couple of said piezo-electric resonators are mounted on said mounting substrate, one being a transmission side filter for processing a transmission signal while another being a reception side filter for processing a reception signal.
